BMT321

1.5-2.8 GHz 1.5W High Linearity 5V 2-Stage Power Amplifier

Package Outline Dimension

---

**NOTES:**

2. CONTROLLING DIMENSIONS: MILLIMETER. CONVERTED INCH
   DIMENSION ARE NOT NECESSARILY EXACT.
3. DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS
   MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. INSULATION THICKNESS, CLEARANCE OF OVERLAP ARE USER DEFINED.
5. INSULATION NOT CORRECTLY SHOWN FOR REASONS OF CLARITY.
**Suggested PCB Land Pattern and PAD Layout**

- **Notes**
  1. Use 1 oz. copper minimum for top and bottom layer metal.
  2. A heatsink underneath the area of the PCB for the mounted device is required for proper thermal operation.
  3. Ground / thermal vias are critical for the proper performance of this device.

**Package Marking**

```
- BMT321
YYWWXX
```

YY = Year, WW = Working Week,
XX = Wafer No.